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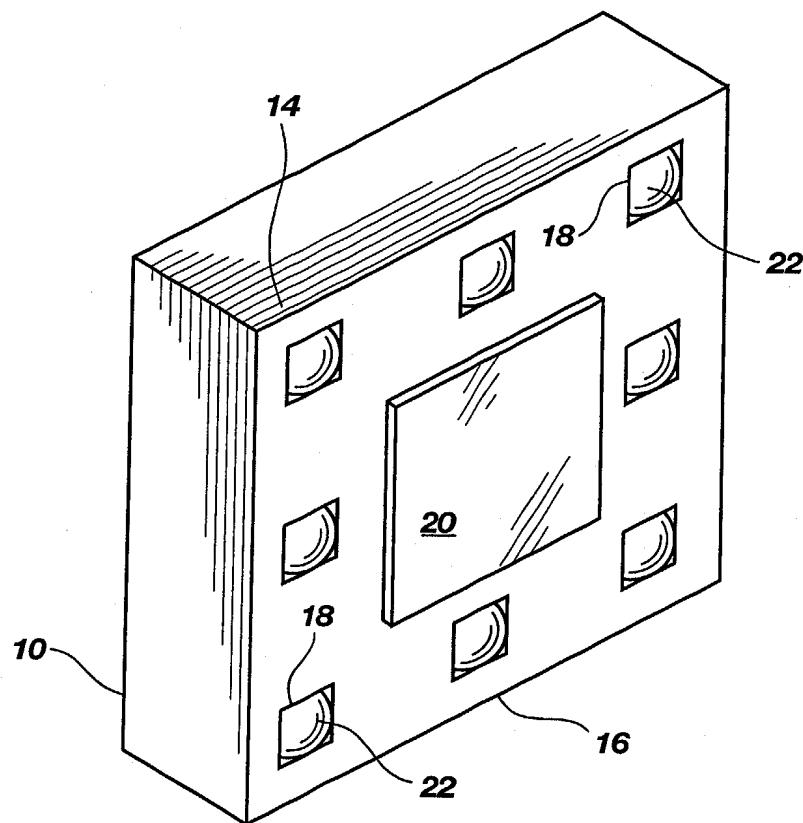


Fig. 1(a)
(PRIOR ART)

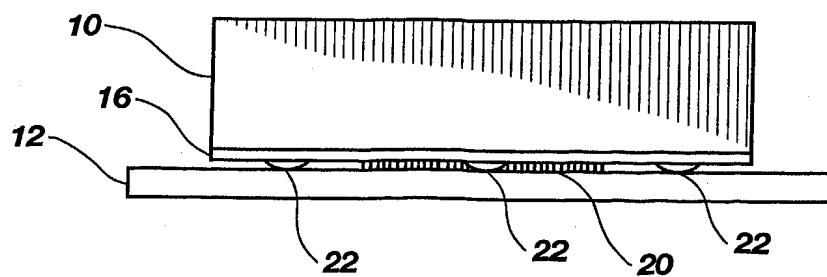


Fig. 1(b)
(PRIOR ART)

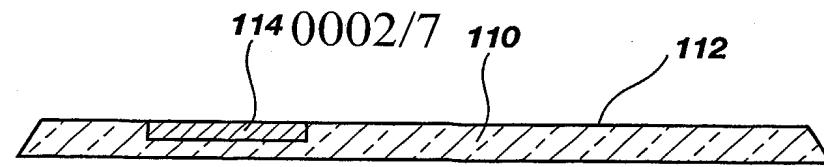


Fig. 2(a)

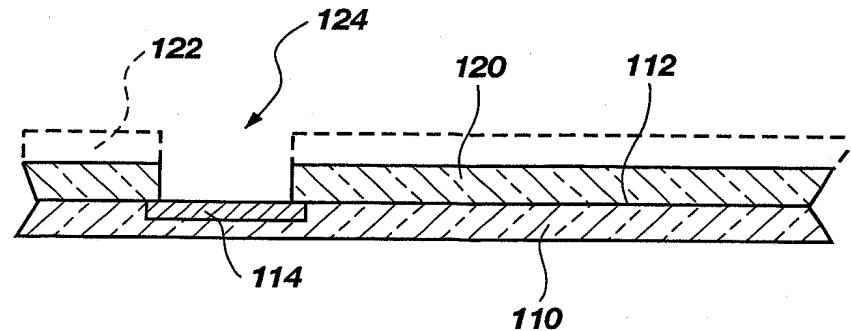


Fig. 2(b)

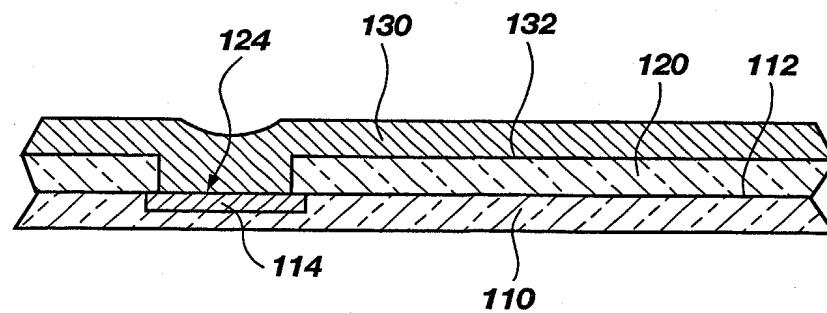


Fig. 2(c)

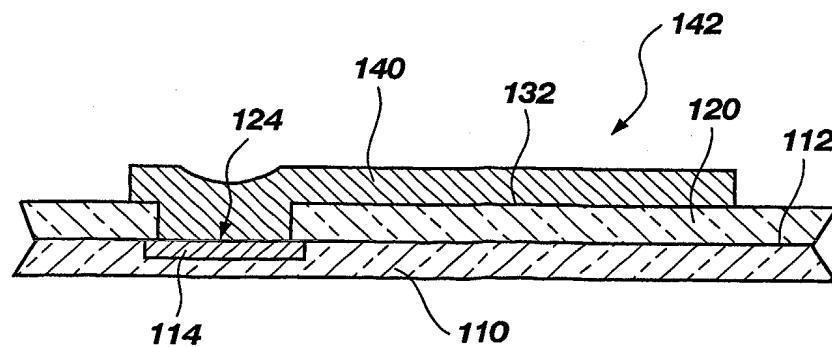


Fig. 2(d)

TITLE: METHOD AND APPARATUS FOR
CONDUCTING HEAT IN A FLIP-CHIP ASSEMBLY
Inventor: Akram et
Docket No.: 4376.1

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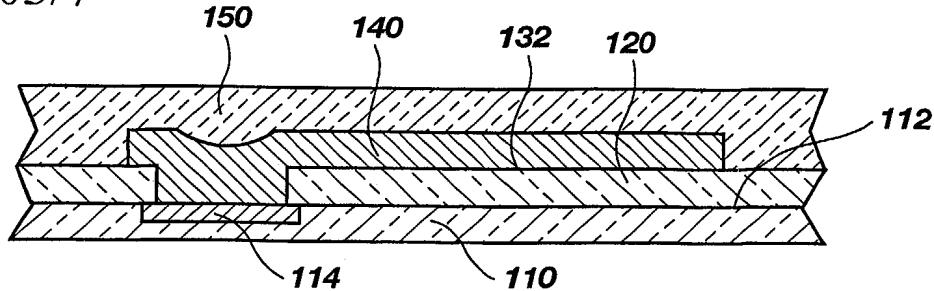


Fig. 2(e)

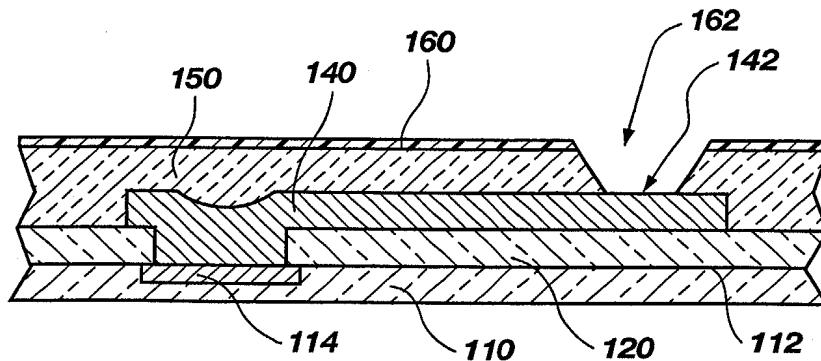


Fig. 2(f)

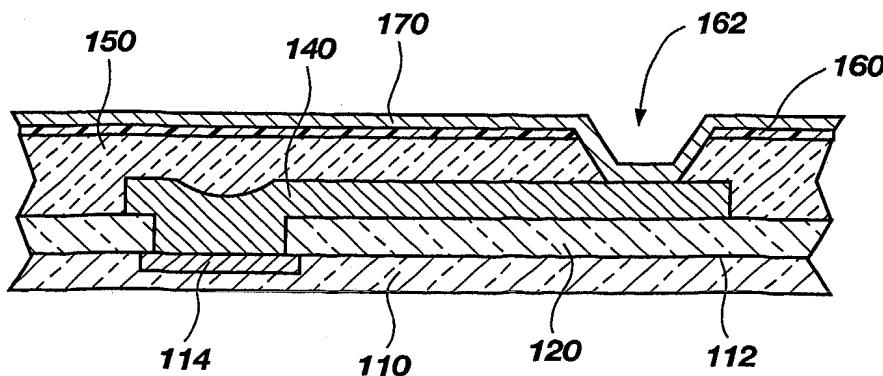


Fig. 2(g)

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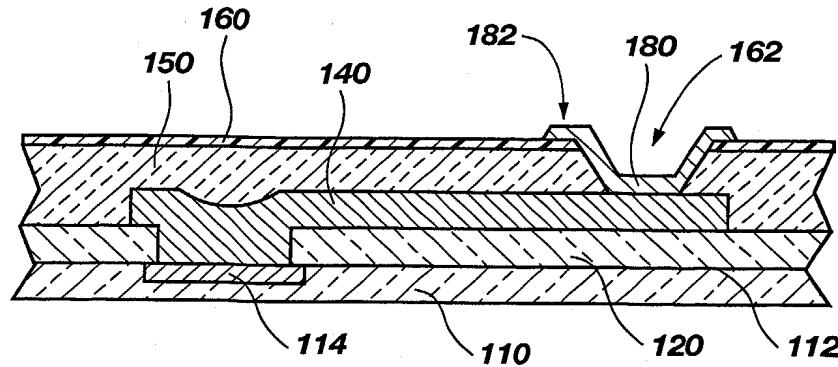


Fig. 2(h)

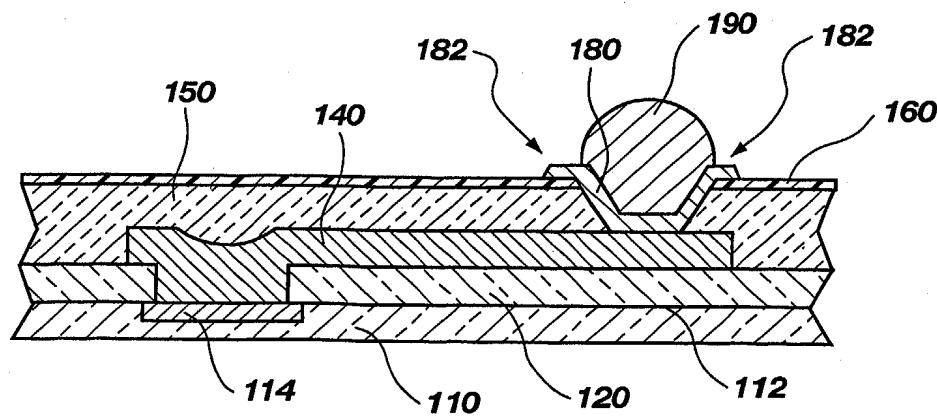


Fig. 2(i)

TITLE: METHOD AND APPARATUS FOR
CONDUCTING HEAT IN A FLIP-CHIP ASSEMBLY
Inventor: Akram et al.
Docket No.: 4376.1US

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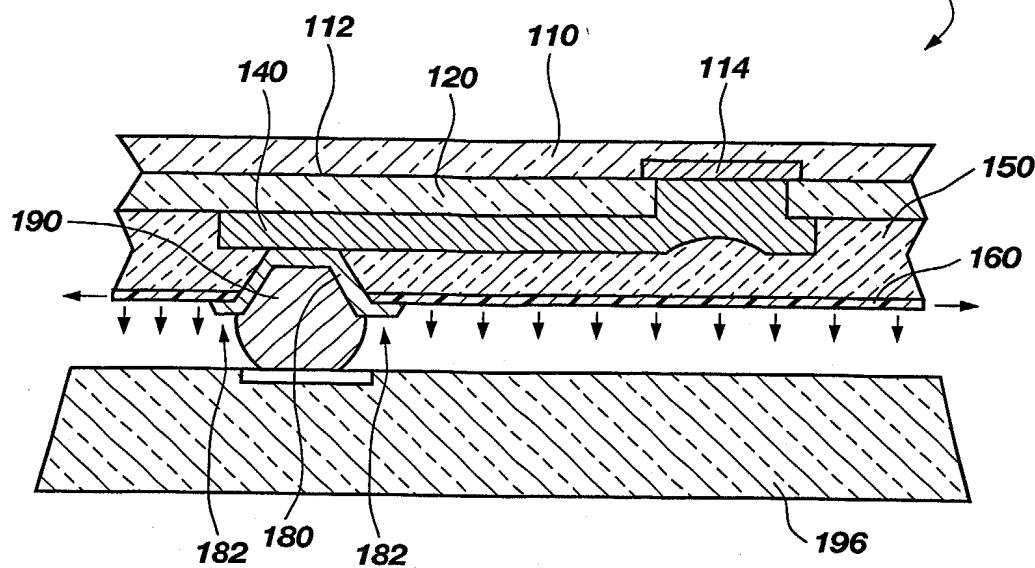


Fig. 3

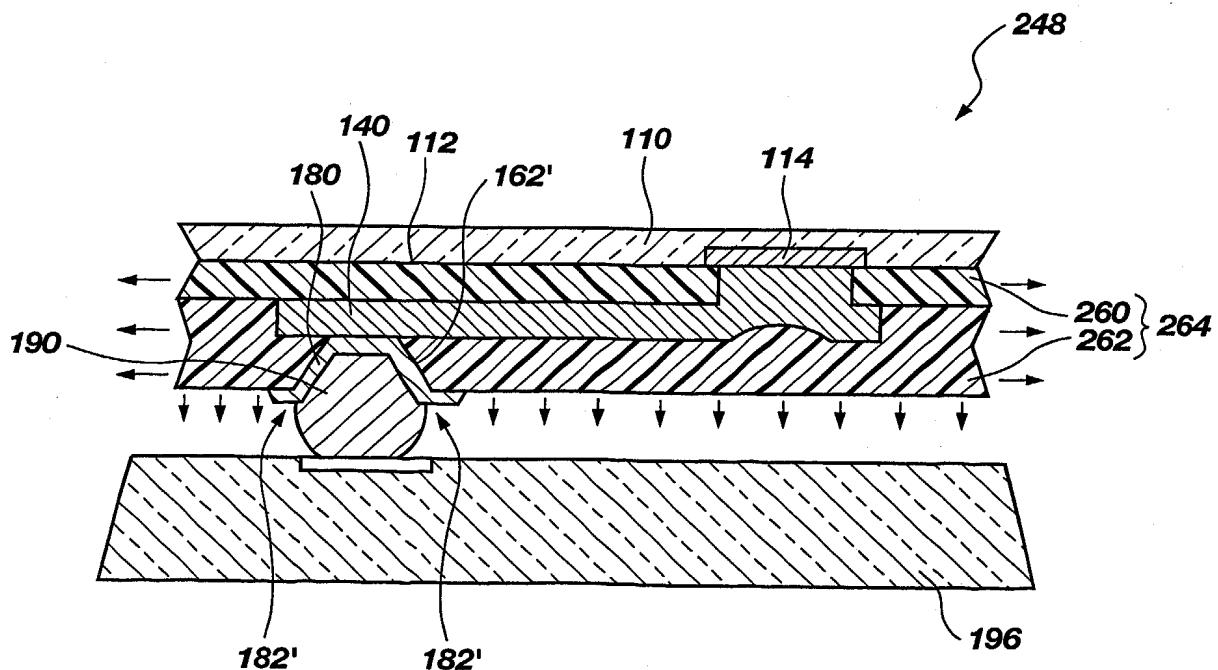


Fig. 4

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Inventor: Akram et al.
Docket No.: 4376.1US

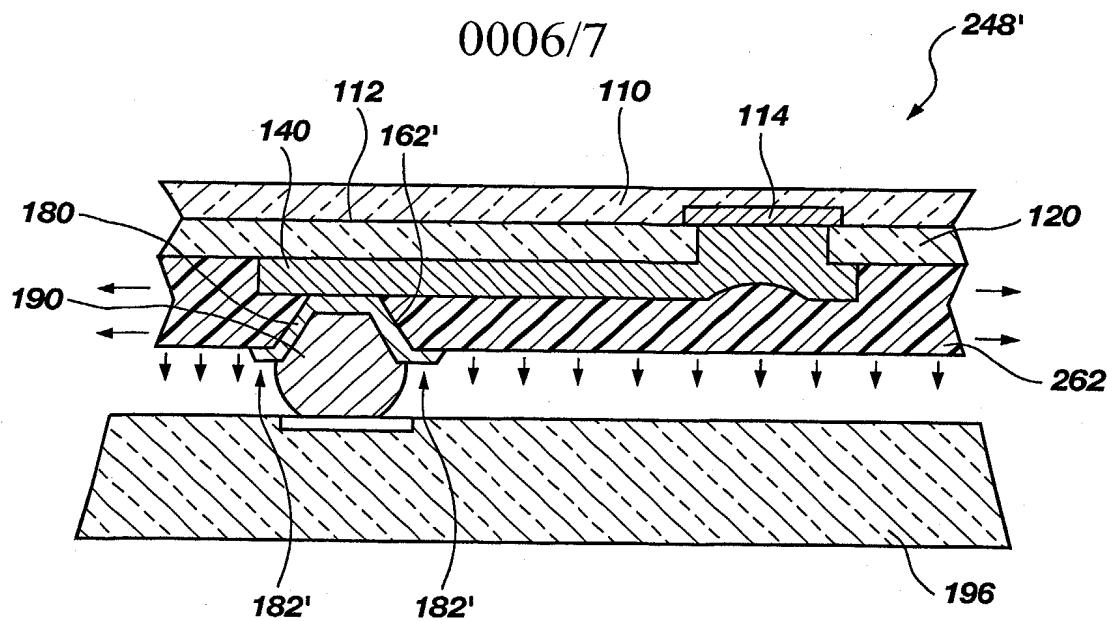


Fig. 5

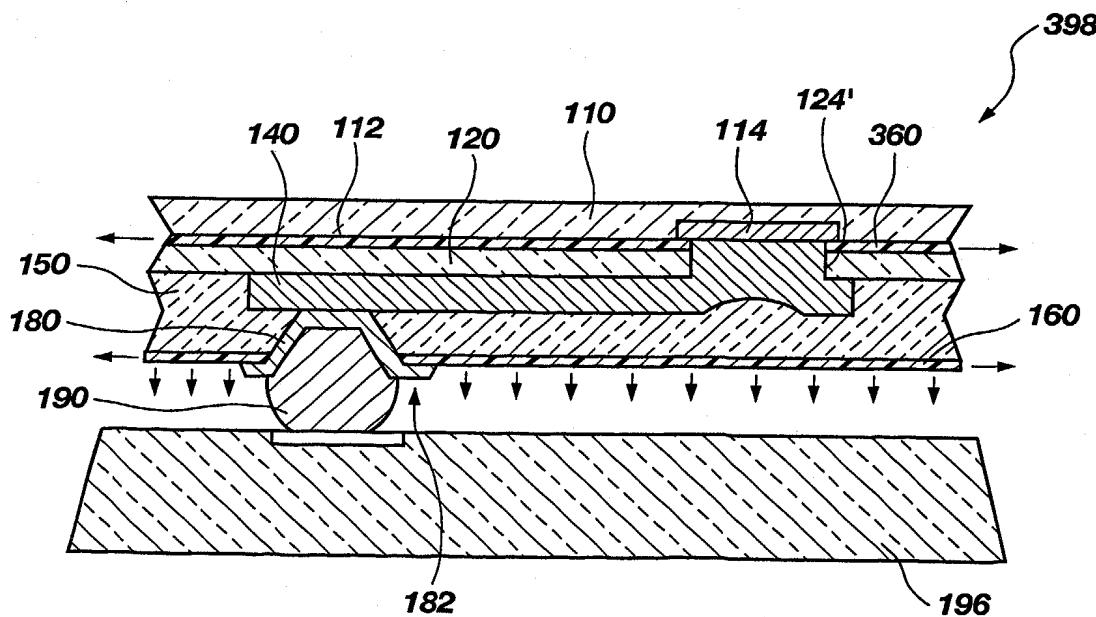


Fig. 6

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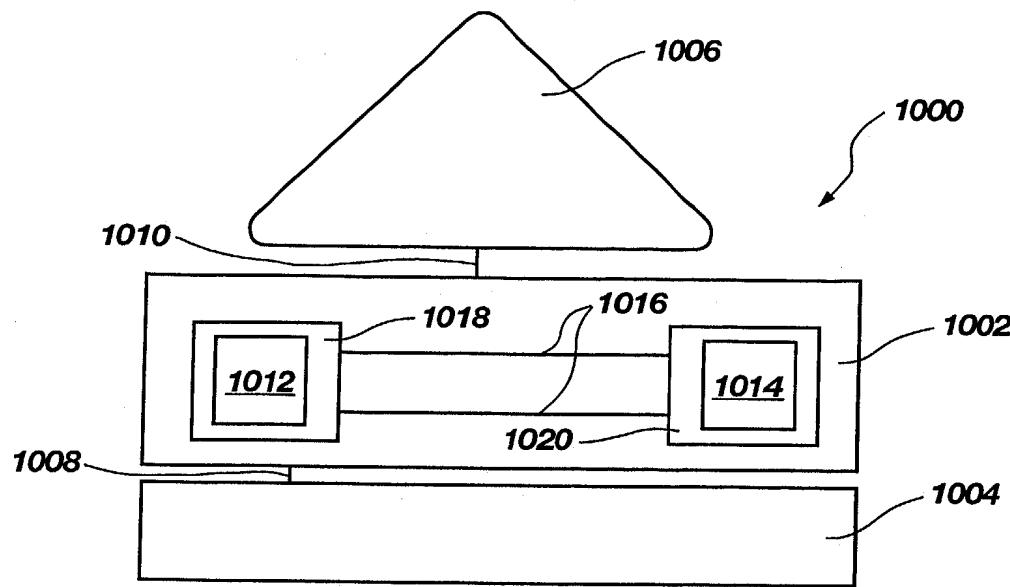


Fig. 7